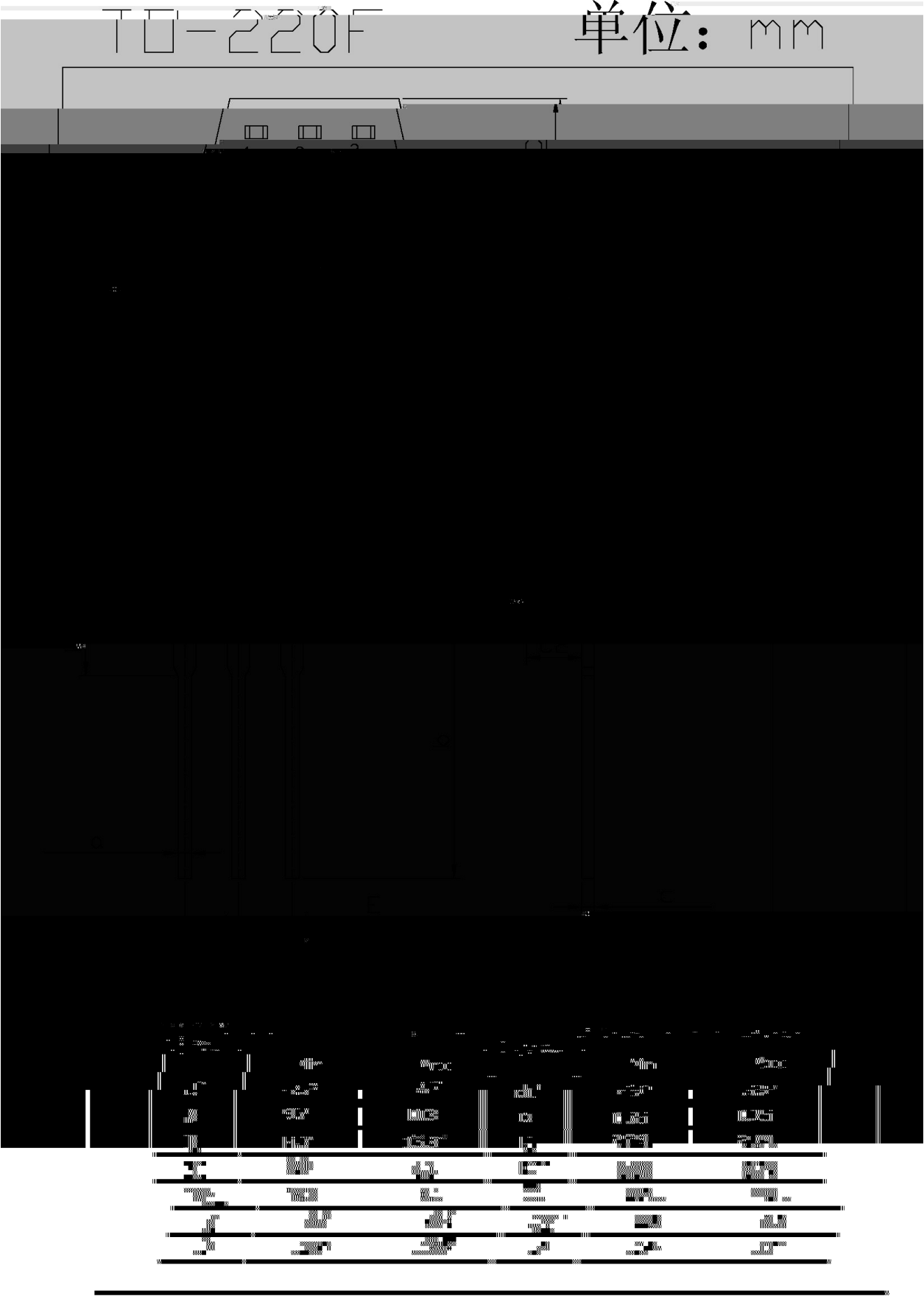


Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	100	V
Working Peak Reverse Voltage	V_{RWM}	100	V
Reverse forward current	I_{FRM}	20	A
Average Forward Current	$I_{F(AV)}$	10	A
Average Forward Current ^{total}	$I_{F(AV)}^{total}$	20	A
Non Repetitive Peak Surge Current	I_{FSM}	150	A
Peak Repetitive Reverse Current	I_{RRM}	0.5	A
Thermal Resistance Junction to Case	$R_{\theta Jc}$	3.5	/W
Junction Temperature Range	T_j	175	
Storage Temperature Range	T_{stg}	-55~175	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Forward Voltage	V_F	$I_F=10A(T_c=25^\circ C)$			0.85	V
		$I_F=10A(T_c=125^\circ C)$			0.7	V
		$I_F=20A(T_c=25^\circ C)$			0.95	V

1



/ Marking Instructions

BR
MBRF20100
CT *****

BR
MBRF20100
CT:

Note:
BR: Company Code
MBRF20100: Product Type Code
CT: Internal Structure
*****:
 Lot No. Code, code change with Lot No.

G PD t ... • Ž Ć (x /) / Temperature Profile for Dip Soldering(Pb-Free)

f → ← f VHF	
a VHF	

7 L P H V H F

a Ć y

10• Ä ½ “ † 25 ½150 - k ž • 60 ½90sec;

20• Q > “ † 255 r5 - k ž • 4 Ò 5 r0.5sec;

30•D N ò i Ò 0 , † 2 ½10 - /sec.

Note:

1.Preheating:25~150 - , Time:60~90sec.

2.Peak Temp.:255 r5 - , Duration:5 r0.5sec.

3. Cooling Speed: 2~10 - /sec.

ÄD /Cã p ¯ »] / Resistance to Soldering Heat Test Conditions

“ † y 270 r5 -

ž • y 10 r1 sec.

Temp.:270±5

Time:10±1 sec

G P á / Packaging SPEC.

• ^ x / BULK

Package Type >û ~ E	Units ;>û !H					Dimension ;>û p . (unit /mm³)		
	Units/Bag >û Ä	Bags/Inner Box >û Ä	Units/Inner Box /-	Inner Boxes/Outer Box - /1ç	Units/Outer Box /1ç	Bag>û Ä	Inner Box	Outer Boxç
TO-220/F	200	10	2,000	5	10,000	135×190	237×172×102	560×245×195

ì ’ x / TUBE

Package Type >û ~ E	Units ;>û !H					Dimension ;>û p . (unit /mm³)		
	Units/Tube /•1×	Tubes/Inner Box •1× /-	Units/Inner Box /-	Inner Boxes/Outer Box - /1ç	Units/Outer Box /1ç	Tube•1×	Inner Box	Outer Boxç
TO-220/F	50	20	1,000	5	5,000	532×31.4×5.5	555×164×50	575×290×180

„ Đ y f / Notices